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In the Abstract:

Please replace the Abstract on file with the following rewritten Abstract:

An electronic package ~~is provided~~ having a surface mount electronic device connected to a circuit board. The package includes a circuit board and a surface mount electronic device. A mounting pad is formed on the circuit board. A plurality of vias are formed each having an opening extending into the circuit board and extending through the mounting pad. The package further includes a solder joint connecting a contact terminal of the surface mount device to the mounting pad on the circuit board. The solder joint extends at least partially into the openings in each of the plurality of vias to support the arrangement of the surface mount device on the circuit board.